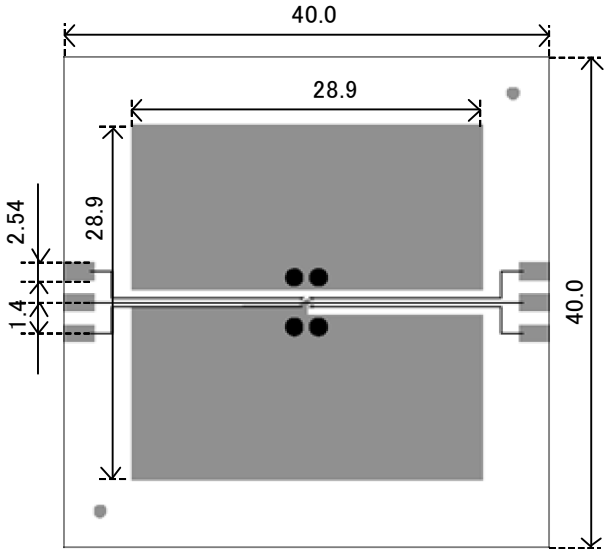
● UFN-4A01 Power Dissipation

Power dissipation data for theUFN-4A01 is shown in this page.
The value of power dissipation varies with the mount board conditions.
Please use this data as the reference data taken in the following condition.

1. Measurement Condition

Condition: Mount on a board
Ambient: Natural convection
Soldering: Lead (Pb) free
Board: Dimensions 40 x 40 mm
(1600 mm2 in one side)
4 Copper Layers
Each layer is connected to the package heat-sink and terminal pin No.1.
Each layer has approximately 800mm2 copper area
Material: Glass Epoxy (FR-4)
Thickness: 1.6mm
Through-hole: 4 x 0.8 Diameter



Evaluation Board (Unit:mm)

2.Power Dissipation vs. Ambient Temperature

Board Mount (Tj max = 125℃)

Ambient Temperature(℃)	Power Dissipation Pd(mW)	Thermal Resistance (℃/W)
25	550	181.82
85	220